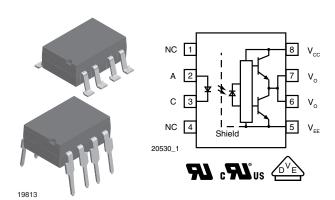


2.5 A Output Current IGBT and MOSFET Driver

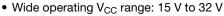


DESCRIPTION

The VO3120 consists of a LED optically coupled to an integrated circuit with a power output stage. This optocoupler is ideally suited for driving power IGBTs and MOSFETs used in motor control inverter applications. The high operating voltage range of the output stage provides the drive voltages required by gate controlled devices. The voltage and current supplied by this optocoupler makes it ideally suited for directly driving IGBTs with ratings up to 800 V/50 A. For IGBTs with higher ratings, the VO3120 can be used to drive a discrete power stage which drives the IGBT gate.

FEATURES

- 2.5 A minimum peak output current
- 25 kV/µs minimum common mode rejection (CMR) at V_{CM} = 1500 V
- I_{CC} = 2.5 mA maximum supply current
- Under voltage lock-out (UVLO) with hysteresis



- 0.2 µs maximum pulse width distortion
- Industrial temperature range: 40 °C to 110 °C
- 0.5 V maximum low level output voltage (V_{OL})
- Reinforced insulation rated per DIN EN 60747-5-2
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Isolated IGBT/MOSFET gate driver
- AC and brushless DC motor drives
- Induction stove top
- Industrial inverters
- Switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

AGENCY APPROVALS

- UL file no. E52744 system code H, double protection
- cUL file no. E52744, equivalent to CSA bulletin 5A
- DIN EN 60747-5-2 (VDE 0884) and reinforced insulation rating available with option 1

ORDERING INFORMATION	
V O 3 1 2 0 - X PART NUMBER	O # # TAPEAND REEL Option 7
PACKAGE	UL, cUL, VDE
DIP-8, tubes	VO3120
DIP-8, tubes	VO3120-X001
SMD-8, option 7, tape and reel	VO3120-X007T

TRUTH TABLE			
LED	V _{CC} - V _{EE} "POSITIVE GOING" (TURN ON)	V _{CC} - V _{EE} "NEGATIVE GOING" (TURN OFF)	Vo
Off	0 V to 32 V	0 V to 32 V	Low
On	0 V to 11 V	0 V to 9.5 V	Low
On	11 V to 13.5 V	9.5 V to 12 V	Transition
On	13.5 V to 32 V	12 V to 32 V	High

2.5 A Output Current IGBT and **MOSFET Driver**



ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT		
INPUT						
Input forward current		l _F	25	mA		
Peak transient input current	< 1 μs pulse width, 300 pps	I _{F(TRAN)}	1	Α		
Reverse input voltage		V _R	5	V		
Output power dissipation		P _{diss}	45	mW		
OUTPUT						
High peak output current (1)		I _{OH(PEAK)}	2.5	Α		
Low peak output current (1)		I _{OL(PEAK)}	2.5	Α		
Supply voltage		(V _{CC} - V _{EE})	0 to + 35	V		
Output voltage		V _{O(PEAK)}	0 to + V _{CC}	V		
Output power dissipation		P _{diss}	250	mW		
OPTOCOUPLER						
Isolation test voltage (between emitter and detector)	t = 1 s	V _{ISO}	5300	V_{RMS}		
Storage temperature range		T _S	- 55 to + 125	°C		
Ambient operating temperature range		T _A	- 40 to + 110	°C		
Total power dissipation		P _{tot}	295	mW		
Lead solder temperature (2)	For 10 s, 1.6 mm below seating plane		260	°C		

- Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. Functional operation of the device is not implied at these or any other conditions in excess of those given in the operational sections of this document. Exposure to absolute maximum ratings for extended periods of the time can adversely affect reliability.
- $^{(1)}$ Maximum pulse width = 10 μ s, maximum duty cycle = 0.2 %. This value is intended to allow for component tolerances for designs with I_{O} peak minimum = 2.5 A. See applications section for additional details on limiting I_{OH} peak.
- (2) Refer to reflow profile for soldering conditions for surface mounted devices (SMD). Refer to wave profile for soldering conditions for through hole devices (DIP).

RECOMMENDED OPERATING CONDITION								
PARAMETER SYMBOL MIN. MAX. UNIT								
Power supply voltage	V _{CC} - V _{EE}	15	32	V				
Input LED current (on)	I _F	7	16	mA				
Input voltage (off)	V _{F(OFF)}	- 3	0.8	V				
Operating temperature	T _{amb}	- 40	+ 110	°C				



2.5 A Output Current IGBT and MOSFET Driver

Vishay Semiconductors

THERMAL CHARACTERISTICS			
PARAMETER	SYMBOL	VALUE	UNIT
LED power dissipation	P _{diss}	45	mW
Output power dissipation	P _{diss}	250	mW
Total power dissipation	P _{tot}	285	mW
Maximum LED junction temperature	T _{jmax.}	125	°C
Maximum output die junction temperature	T _{jmax} .	125	°C
Thermal resistance, junction emitter to board	θ_{JEB}	169	°C/W
Thermal resistance, junction emitter to case	$\theta_{\sf JEC}$	192	°C/W
Thermal resistance, junction detector to board	θ_{JDB}	82	°C/W
Thermal resistance, junction detector to case	θ_{JDC}	80	°C/W
Thermal resistance, junction emitter to junction detector	θ_{JED}	200	°C/W
Thermal resistance, case to ambient	$\theta_{\sf CA}$	2645	°C/W

Note

The thermal characteristics table above were measured at 25 °C and the thermal model is represented in the thermal network below. Each
resistance value given in this model can be used to calculate the temperatures at each node for a given operating condition. The thermal
resistance from board to ambient will be dependent on the type of PCB, layout and thickness of copper traces. For a detailed explanation
of the thermal model, please reference Vishay's Thermal Characteristics of Optocouplers application note.

ELECTRICAL CHARACTERISTIC	cs					
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
High lovel output gurrent	V _O = (V _{CC} - 4 V)	I _{OH} ⁽¹⁾	0.5			Α
High level output current	V _O = (V _{CC} - 15 V)	I _{OH} ⁽²⁾	2.5			Α
Low level output ourrent	$V_{O} = (V_{EE} + 2.5 \text{ V})$	I _{OL} (1)	0.5			Α
Low level output current	$V_{O} = (V_{EE} + 15 V)$	I _{OL} (2)	2.5			Α
High level output voltage	I _O = - 100 mA	V _{OH} (3)	V _{CC} - 4			V
Low level output voltage	I _O = 100 mA	V _{OL}		0.2	0.5	V
High level supply current	Output open, I _F = 7 mA to 16 mA	I _{CCH}			2.5	mA
Low level supply current	Output open, $V_F = -3 \text{ V to} + 0.8 \text{ V}$	I _{CCL}			2.5	mA
Threshold input current low to high	$I_{O} = 0 \text{ mA}, V_{O} > 5 \text{ V}$	I _{FLH}			5	mA
Threshold input voltage high to low		V_{FHL}	0.8			V
Input forward voltage	I _F = 10 mA	V_{F}	1		1.6	V
Temperature coefficient of forward voltage	I _F = 10 mA	$\Delta V_F / \Delta T_A$		- 1.4		mV/°C
Input reverse breakdown voltage	I _R = 10 μA	BV _R	5			V
Input capacitance	f = 1 MHz, V _F = 0 V	C _{IN}		60		pF
UVLO threshold	$V_O \ge 5 \text{ V}$	V _{UVLO+}	11		13.5	V
OVLO tilleshold	I _F = 10 mA	V _{UVLO} -	9.5		12	V
UVLO hysteresis		UVLO _{HYS}		1.6		V

- Minimum and maximum values were tested over recommended operating conditions (T_A = 40 °C to 110 °C, I_{F(ON)} = 7 mA to 16 mA, V_{F(OFF)} = 3 V to 0.8 V, V_{CC} = 15 V to 32 V, V_{EE} = ground) unless otherwise specified. Typical values are characteristics of the device and are the result of engineering evaluations. Typical values are for information only and are not part of the testing requirements. All typical values were measured at T_{amb} = 25 °C and with V_{CC} V_{EE} = 32 V.
- $^{(1)}$ Maximum pulse width = 50 μ s, maximum duty cycle = 0.5 %.
- (2) Maximum pulse width = 10 μ s, maximum duty cycle = 0.2 %. This value is intended to allow for component tolerances for designs with I_0 peak minimum = 2.5 A.
- (3) In this test V_{OH} is measured with a dc load current. When driving capacitive loads V_{OH} will approach V_{CC} as I_{OH} approaches zero A. Maximum pulse width = 1 ms, maximum duty cycle = 20 %.

2.5 A Output Current IGBT and MOSFET Driver



TEST CIRCUITS

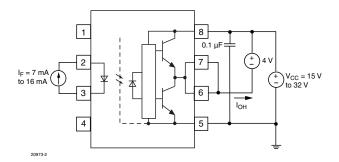
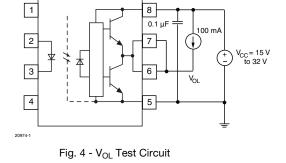


Fig. 1 - I_{OH} Test Circuit



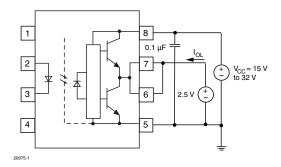


Fig. 2 - I_{OL} Test Circuit

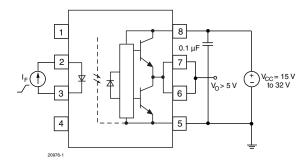


Fig. 5 - I_{FLH} Test Circuit

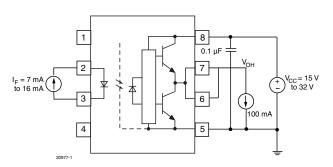


Fig. 3 - V_{OH} Test Circuit

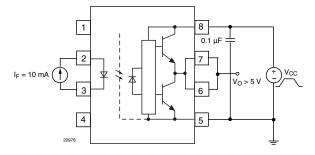


Fig. 6 - UVLO Test Circuit

SWITCHING CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Propagation delay time to logic low output (1)	$R_g = 10 \ \Omega, \ C_g = 10 \ \text{nF, f} = 10 \ \text{kHz},$ $\text{duty cycle} = 50 \ \%$	t _{PHL}	0.1		0.4	μs
Propagation delay time to logic high output ⁽¹⁾	$R_g = 10 \Omega$, $C_g = 10 nF$, $f = 10 kHz$, duty cycle = 50 %	t _{PLH}	0.1		0.4	μs
Pulse width distortion (2)	$R_g = 10 \ \Omega, \ C_g = 10 \ \text{nF, f} = 10 \ \text{kHz}, \\ \text{duty cycle} = 50 \ \%$	PWD			0.2	μs
Rise time	$R_g = 10 \ \Omega, \ C_g = 10 \ \text{nF, f} = 10 \ \text{kHz}, \\ \text{duty cycle} = 50 \ \%$	t _r		0.1		μs



2.5 A Output Current IGBT and MOSFET Driver

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SWITCHING CHARACTERISTICS							
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Fall time	$R_g = 10 \ \Omega, \ C_g = 10 \ \text{nF, f} = 10 \ \text{kHz}, \\ \text{duty cycle} = 50 \ \%$	t _f		0.1		μs	
UVLO turn on delay	$V_{O} > 5 \text{ V, I}_{F} = 10 \text{ mA}$	T _{UVLO-ON}		0.8		μs	
UVLO turn off delay	$V_{O} < 5 \text{ V}, I_{F} = 10 \text{ mA}$	T _{UVLO-OFF}		0.6		μs	

Notes

- $^{(1)}$ This load condition approximates the gate load of a 1200 V/75 A IGBT.
- $^{(2)}$ Pulse width distortion (PWD) is defined as $|t_{PHL}-t_{PLH}|$ for any given device.
- (3) The difference between t_{PHL} and t_{PLH} between any two VO3120 parts under the same test condition.

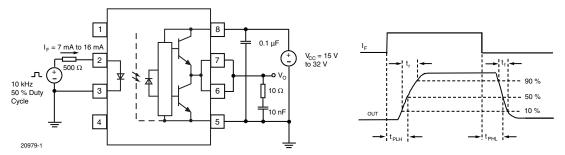


Fig. 7 - t_{PLH} , t_{PHL} , t_{r} and t_{f} Test Circuit and Waveforms

COMMON MODE TRANSIENT IMMUNITY							
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT	
Common mode transient immunity at logic high output (1)(2)	$T_A = 25$ °C, $I_F = 10$ mA to 16 mA, $V_{CM} = 1500$ V, $V_{CC} = 32$ V	CM _H	25	35		kV/μs	
Common mode transient immunity at logic low output (1)(3)	$T_A = 25$ °C, $V_{CM} = 1500$ V, $V_{CC} = 32$ V, $V_F = 0$ V	CM _L	25	35		kV/μs	

- ⁽¹⁾ Pins 1 and 4 need to be connected to LED common.
- (2) Common mode transient immunity in the high state is the maximum tolerable $|dV_{CM}/dt|$ of the common mode pulse, V_{CM} , to assure that the output will remain in the high state (i.e., $V_O > 15$ V).
- (3) Common mode transient immunity in a low state is the maximum tolerable |dV_{CM}/dt| of the common mode pulse, V_{CM}, to assure that the output will remain in a low state (i.e., V_O < 1 V).</p>

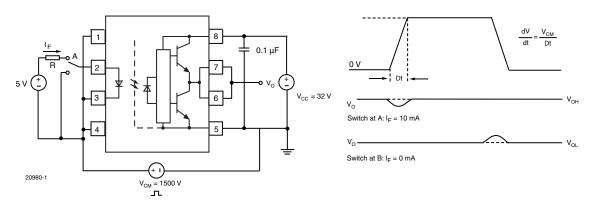


Fig. 8 - CMR Test Circuit and Waveforms

2.5 A Output Current IGBT and MOSFET Driver



SAFETY AND INSULATION	RATINGS					
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Climatic classification (according to IEC 68 part 1)				40/110/21		
Comparative tracking index		CTI	175		399	
Peak transient overvoltage		V _{IOTM}	8000			V
Peak insulation voltage		V _{IORM}	890			V
Safety rating - power output		P _{SO}			500	mW
Safety rating - input current		I _{SI}			300	mA
Safety rating - temperature		T _{SI}			175	°C
Creepage distance	Standard DIP-8		7			mm
Clearance distance	Standard DIP-8		7			mm
Creepage distance	400 mil DIP-8		8			mm
Clearance distance	400 mil DIP-8		8			mm

Note

TYPICAL CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

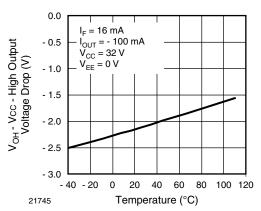


Fig. 9 - High Output Voltage Drop vs. Temperature

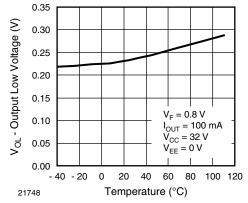


Fig. 11 - Output Low Voltage vs. Temperature

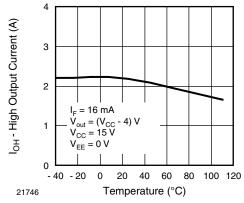


Fig. 10 - High Output Current vs. Temperature

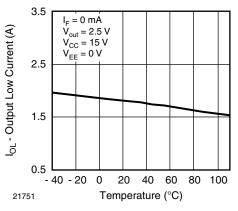


Fig. 12 - Output Low Current vs. Temperature

[•] As per IEC 60747-5-2, §7.4.3.8.1, this optocoupler is reinforced rated and suitable for "safe electrical insulation" only within the safety ratings. Compliance with the safety ratings shall be ensured by means of protective circuits.



2.5 A Output Current IGBT and **MOSFET Driver**

2.5

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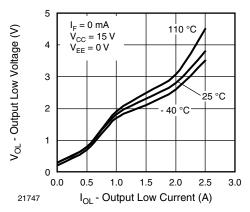
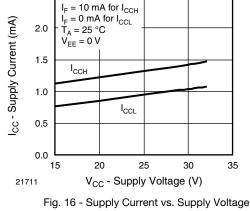


Fig. 13 - Output Low Voltage vs. Output Low Current



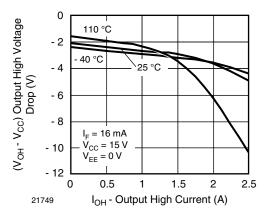


Fig. 14 - Output High Voltage Drop vs. Output High Current

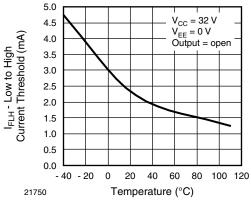


Fig. 17 - Low to High Current Threshold vs. Temperature

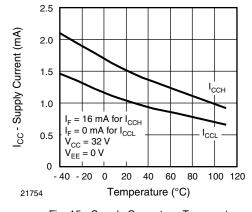


Fig. 15 - Supply Current vs. Temperature

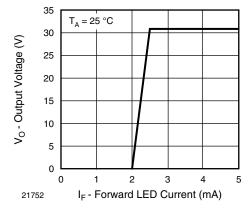


Fig. 18 - Transfer Characteristics

2.5 A Output Current IGBT and MOSFET Driver



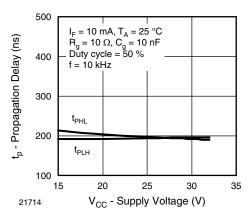


Fig. 19 - Propagation Delay vs. Supply Voltage

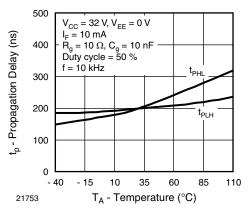


Fig. 20 - Propagation Delay vs. Temperature

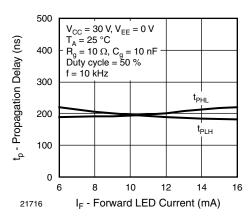


Fig. 21 - Propagation Delay vs. Forward LED Current

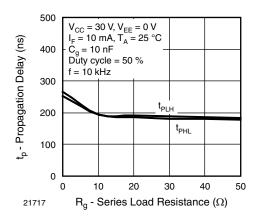


Fig. 22 - Propagation Delay vs. Series Load Resistance

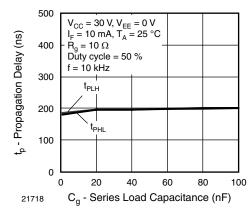


Fig. 23 - Propagation Delay vs. Series Load Capacitance

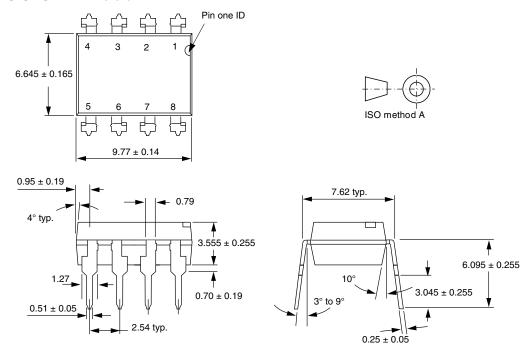
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2.5 A Output Current IGBT and MOSFET Driver

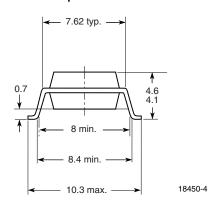
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PACKAGE DIMENSIONS in millimeters

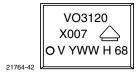


i178006

Option 7



PACKAGE MARKING



- The VDE logo is only marked on option 1 parts.
- Tape and reel suffix (T) is not part of the package marking.





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